

Sub E1
D3 --29. (Amended) An ink jet printing module comprising a piezoelectric element having a surface, and a thermoplastic bonding component, the thermoplastic bonding component having dimensions of a surface of a first component heat-bonded to the surface.--

D4 Sub E1 --46. (Amended) A method of manufacturing an ink jet printing module comprising:
contacting a first component of an ink jet printing module having a surface with a thermoplastic bonding component;
contacting a second component of the ink jet printing module including a orifice plate having a surface with the thermoplastic bonding component; and
adhering a peelable protector strip over the orifice plate.--

Please add new claims 47 to 65.

Rule 1.56
25 *50*
47. --~~47~~. (New) The method of claim 1 wherein the thermoplastic bonding component includes a plurality of openings.--

Sub E1 *48*
--~~48~~. (New) The method of claim 21 wherein the thermoplastic bonding component includes a plurality of openings.--

49
--~~49~~. (New) The ink jet module of claim 29 wherein the thermoplastic bonding component includes a plurality of openings.--

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--~~50~~. (New) The method of claim 45 wherein the filter includes a repeating pattern of units having a plurality of openings.--

51
--~~51~~. (New) The method of claim *50*, wherein a land between the units is at least 50 microns.

⁵²
~~52~~ (New) An ink jet printing module comprising a piezoelectric element having a surface, and a thermoplastic bonding component heat-bonded to the surface,

wherein the thermoplastic bonding component has a thickness between 1 micron and 150 microns.--

⁵³
~~53~~ (New) The ink jet printing module of claim ⁵²~~52~~, wherein the thermoplastic bonding component has a thickness between 10 microns and 125 microns.--

⁵⁴
~~54~~ (New) The ink jet printing module of claim ⁵²~~52~~, wherein the thermoplastic bonding component has a thickness between 20 and 50 microns.--

⁵⁵
~~55~~ (New) The ink jet printing module of claim ⁵²~~52~~, wherein the thermoplastic bonding component includes a first surface heat-bonded to the surface of the piezoelectric element and a second surface heat-bonded to a surface of an ink jet printing module component.--

⁵⁶
~~56~~ (New) The ink jet printing module of claim ⁵²~~52~~, wherein the thermoplastic bonding component includes an electrode pattern.--

⁵⁷
~~57~~ (New) The ink jet printing module of claim ⁵²~~52~~, wherein the piezoelectric element is lead zirconium titanate.--

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~~58~~ (New) The ink jet printing module of claim ⁵²~~52~~, wherein the thermoplastic bonding component includes a polyimide.--

⁵⁹
~~59~~ (New) The ink jet printing module of claim ⁵²~~52~~, further comprising an ink channel, the piezoelectric element being positioned to subject ink within the channel to jetting pressure, and electrical contacts arranged for activation of the piezoelectric element.--

⁶⁰
~~60~~ (New) The ink jet printing module of claim ⁵⁹~~59~~, further comprising a series of channels.--

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~~64~~
--~~61~~. (New) The ink jet printing module of claim ~~60~~⁶⁰, wherein each of said channels is covered by a single piezoelectric element.--

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~~65~~
--~~62~~. (New) The ink jet printing module of claim ~~59~~⁵⁹, wherein the thermoplastic bonding component covers the ink channel and includes a filter.--

Sub
E1
63
~~66~~
--~~63~~. (New) The ink jet printing module of claim ~~62~~⁶², wherein the filter including a repeating pattern of units having a plurality of openings and a land between the units is at least 50 microns.--

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~~67~~
--~~64~~. (New) The ink jet printing module of claim ~~63~~⁶³, wherein the width is 300 to 495 microns.--

~~68~~ 65
--~~65~~. (New) The ink jet printing module of claim ~~52~~⁵², further comprising an orifice plate and a protector strip adhered to the orifice plate, wherein either the orifice plate or the protector strip includes a thermoplastic bonding material.--